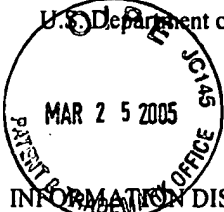


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 <p>U.S. Department of Commerce, Patent and Trademark Office</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p>(Use several sheets if necessary)</p>	Application No.:	10/813,407
	Filing Date:	March 29, 2004
	First Named Inventor:	Jiping Li
	Group Art Unit:	2811 2822
	Examiner Name:	Unknown
	Confirmation No.:	5642
	Attorney Docket No.:	BOX016 US

U.S. Patent Documents

*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
MT	1.	6,489,801	12/3/02	Borden et al.	324	766	
	2.	6,812,047	11/2/04	Borden et al.	438	16	
	3.	5,966,019	10/12/99	Borden	324	752	
	4.	5,377,006	12/27/94	Nakata	356	349	
	5.	6,323,951	11/27/01	Borden et al.	356	502	
	6.	6,426,644	7/30/02	Borden et al.	324	765	
	7.	5,042,951	8/27/91	Gold et al.	356	369	
	8.	5,159,412	10/27/92	Willenborg et al.	356	445	
	9.	5,181,080	1/19/93	Fanton et al.	356	381	
	10.	5,228,776	7/20/93	Smith et al.	374	5	
	11.	4,255,971	3/17/81	Rosencwaig	73	606	
	12.	4,579,463	4/1/86	Rosencwaig et al.	374	57	
	13.	4,632,561	12/30/86	Rosencwaig et al.	356	432	
	14.	4,636,088	1/13/87	Rosencwaig et al.	374	5	
	15.	4,750,822	6/14/88	Rosencwaig et al.	324	445	
	16.	6,049,220	4/11/00	Borden et al.	324	765	
	17.	6,483,594	11/19/02	Borden et al.	356	502	
	18.	6,154,280	11/2/00	Borden	356	376	
	19.	6,054,868	4/25/00	Borden et al.	324	752	
	20.	5,883,518	3/16/99	Borden	324	752	
	21.	5,877,860	3/2/99	Borden	356	376	
	22.	5,978,074	11/2/99	Opsal et al.	356	72	
	23.	6,268,916	7/31/01	Lee et al.	356	432	
	24.	5,574,562	11/12/96	Fishman et al.	356	432	
	25.	6,169,601	1/2/01	Eremin et al.	356	240	

Examiner: Michael Trinh	Date Considered: 9/27/05
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	Group Art Unit:	2811
	Examiner Name:	Unknown
	Confirmation No.:	5642
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MT	26.	3,803,413	4/9/74	Vanzetti et al.	250	338	
	27.	2002/0126732A1	9/12/02	Shakouri et al.	374	130	
	28.	6,327,035	12/4/01	Li et al.	356	432	
	29.	6,281,027	9/28/01	Wei et al.	438	14	
	30.	4,950,990	8/21/90	Moulder	324	224	
	31.	4,521,118	06/00/85	Rosencwaig	374	5	
	32.	5,074,669	12/1/91	Opsal	356	447	
	33.	3,909,602	9/30/75	Micka	716	4	
	34.	5,790,251	8/4/98	Hagiwara	356	351	
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	39.	4,795,260	1/3/89	Schuur et al.	356	400	
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	42.	3,462,602	8/16/67	Apple	250	83	
	43.	5,149,978	9/22/92	Opsal et al.	250	234	
	44.	6,400,454	6/4/02	Noguchi et al.	356	237	
✓	45.	4,679,946	7/14/87	Rosencwaig et al.	374	5	
MT	46.	6,694,284 B1	2/17/04	Nikoonahad et al.	702	155	

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							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
MT	47.	0 718 595	20.12.95	EP	G01B	6-Nov		
MT	48.	2000 009443A	Jan-00	JP	G01B			
MT	49.	405006929A	Jan-93	JP	H01L	21/66		

Examiner: <i>Michael Trinh</i>	Date Considered: <i>9/27/05</i>
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	Group Art Unit:	2811 2822
	Examiner Name:	Unknown
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MT	50.	ISR PCT/ US99/12999	09.06.1999	WO	G01L	21/17		
	51.	ISR PCT/US03/06239	02.28.2003	WO	G01L	21/55		
	52.	ISR PCT/US01/07475	07.03.2001	WO				
MT	53.	ISR PCT/US03/06379	02.28.2003	WO	G01N	21/88		
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
MT	54.	Paquin, "Properties of Metals", Handbook of Optics, Vol. II, McGraw-Hill, Inc. (month unavailable), 1995, pp. 35.3-35.7						
	55.	Rosencwaig et al. "Detection of Thermal Waves Through Optical Reflectance", Appl Phys. Lett. 46, June 1985, pp1013-1015						
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	67.	H.S. Carslaw and J.C. Jaeger, "Conduction of Heat In Solids", Second Edition, published prior to March 1, 2002, pages 64-66						
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	Filing Date:	March 29, 2004
	First Named Inventor:	Jiping Li
	Group Art Unit:	2841 <i>2822</i>
	Examiner Name:	Unknown
	Confirmation No.:	5642
	Attorney Docket No.:	BOX016 US

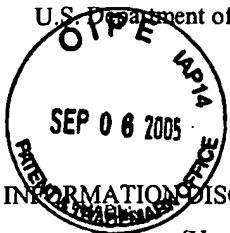
<i>MT</i>	69.	A. Rosencwaig et al., "Thin-Film Thickness Measurements with Thermal Waves", Journal De Physique, October 1983, pp. C6-483 - C6-489
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	85.	W. Lee Smith, "Direct Measurement of Stress-Induced Void Growth by Thermal Wave Modulated Optical Reflectance Imaging", 1991 IEEE/IRPS, pp 200-208
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<i>MT</i>	87.	C. G. Welles et al., "High-Resolution Thermal Wave Imaging of Surface and Subsurface Defects in IC Metal Lines", Materials Research Society, SF Marriott, April 27-May 1, 1992, pp 1187-1191

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MT	88.	J. A. Batista et al., "Biased MOS-FET and Polycrystalline Silicon Tracks Investigated by Photothermal Reflectance Microscopy", pp 468-469
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	91.	9th International Conference on Photoacoustic and Photothermal Phenomena Conference Digest, June 27-30, 1996 Nanjing, P.R. China, pp 81
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	98.	US Appl. No. 10/722,724 entitled "Apparatus and Method For Measuring A Property of a Layer in a Multilayered Structure"
	99.	US Appl. No. 10/090,316 entitled "Apparatus and Method For Measuring A Property Of A Layer In A Multilayered Structure"
	100.	US Appl. No. 09/521,232 entitled "Evaluating A Property Of A Multilayered Structure"
	101.	US Appl. No. 10/977,380 entitled "Evaluating A Property Of A Multilayered Structure"
	102.	US Appl. No. 09/788,273 entitled "Evaluating Sidewall Coverage In A Semiconductor Wafer"
	103.	US Appl. No. 10/090,262 entitled "Evaluating A Multilayered Structure For Voids"
	104.	US Appl. No. 10/984,463 entitled "Evaluating A Multilayered Structure For Voids"
	105.	US Appl. No. 10/090,287 entitled "Identifying Defects In A Conductive Structure Of A Wafer, Based On Heat Transfer Therethrough"
MT	106.	US Appl. No. 10/979,397 entitled "Evaluation Of Openings In A Dielectric Layer"

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U.S. Patent Documents

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MT	107	6,040,936	3/21/01	Kim et al.	359	245	
	108	6,720,248	4/13/04	Ryo	438	622	
	109	6,747,355	6/8/04	Abiru	257	758	
	110	4,873,434	10/10/89	See et al.	250	235	
	111	6,541,747 B1	4/1/03	Kikuchi et al.	250	201	
	112	2002/0167326 A1	11/14/02	Borden et al.	324	752	
	113	2003/0165178 A1	9/4/03	Borden et al.	374	5	
	114	6,387,715	5/14/02	David et al.	438	16	
	115	2001/0017878 A1	8/30/01	Nozoe et al.	374	7	
	116	6,330,361	12/11/01	Mitchell et al.	382	211	
	117	4,201,087	5/6/80	Akita et al.	73	339	
	118	6,178,020	1/23/01	Schultz et al.	359	107	
	119	5,128,864	7/7/92	Waggener et al.	364	413	
MT	120	5,304,931	4/19/94	Flamig et al.	324	309	
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)							
MT	121	J.M. Ziman, F.R.S., "Principles of the Theory of Solids", 2nd Edition, Cambridge At the University Press 1972, pp 278-282					
	122	Chung Wah See and Mehdi Vaez-Iravani, "Differential amplitude scanning optical microscope: theory and applications", Applied Optics Vol. 27, No. 13, July 1, 1988, pp 2786-2792					
	123	International Search Report in PCT/US03/06250 which claims priority of US Application 10/090,287					
	124	Written Opinion in PCT/US99/12999 which claims priority of US Application 09/095,805					
MT	125	Communication Relating To Results of Partial International Search in PCT/US05/009588, which claims priority of US Application 10/813,407 (<i>current application</i>)					

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